

Standard unfilled appliance grade - improved stain resistance Celcon® M90-34 is a specially formulated injection moldable grade of acetal copolymer for the appliance market targeted at resisting staining while providing a balance of properties. Chemical abbreviation according to ISO 1043-1: POM

Rheological properties

Melt volume-flow rate Temperature Load Moulding shrinkage, parallel Moulding shrinkage, normal	8 190 2.16 2.2 1.8	kg %	ISO 1133 ISO 294-4, 2577 ISO 294-4, 2577
Typical mechanical properties			
Tensile Modulus Yield stress, 50mm/min Yield strain, 50mm/min Flexural Modulus Charpy notched impact strength, 23°C Izod notched impact strength, 23°C	11 2450 7.4	MPa %	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 179/1eA ISO 180/1A
Thermal properties			
Melting temperature, 10°C/min Temp. of deflection under load, 1.8 MPa	165 100	-	ISO 11357-1/-3 ISO 75-1/-2
Other properties			
Humidity absorption, 2mm Water absorption, 2mm Density	0.2 0.75 1410		Sim. to ISO 62 Sim. to ISO 62 ISO 1183
Injection			
Drying Temperature Drying Time, Dehumidified Dryer Melt Temperature Optimum Max. mould temperature Back pressure Injection speed	100 - 120 3 - 4 174 80 - 120 4 slow-medium	h °C	Internal

Additional information

Injection molding

Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio

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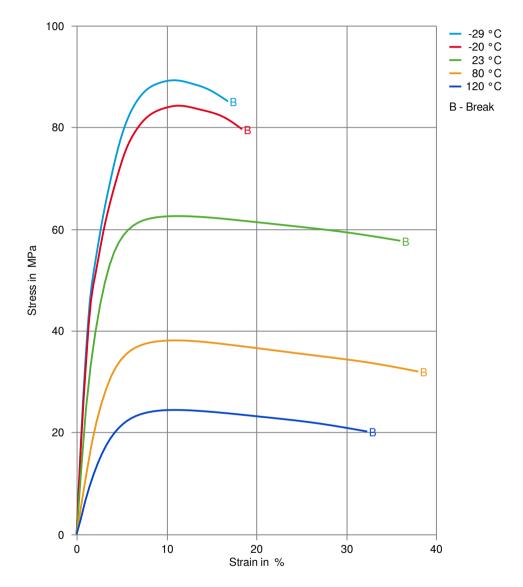
may lead to excessive shear heating and deterioration of the material.

Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F).

Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.

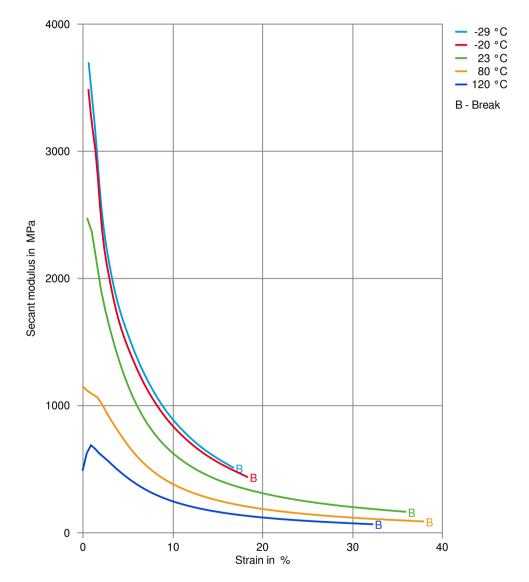


Stress-strain



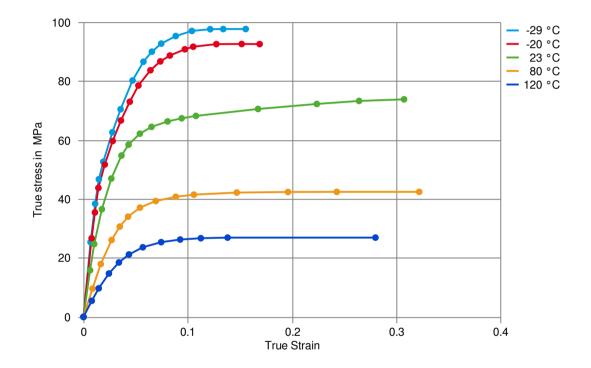


Secant modulus-strain





True stress-strain





Processing Texts	
Pre-drying	Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.
Injection molding	Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material.
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Injection molding Preprocessing	Drying is generally not required because Celcon® and Hostaform® acetal copolymers are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3hours. Desiccant hopper dryers are not required. Maximum water content = 0.35%
Injection molding Postprocessing	Postprocessing conditioning and moisturizing are not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.



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